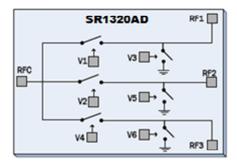
# DC TO 20GHz GaAs SP3T SWITCH

## **SR1320AD**

The SR1320AD is a reflective SP3T GaAs microwave monolithic integrated circuit (MMIC) switch. The SR1320AD is developed for broadband communications, instrumentation, and electronic warfare.



# **KEY CHARACTERISTICS**

- Low Insertion Loss: 1.6dB at 20GHz
- High Isolation: 42dB at 20GHz
- Excellent Return Loss
- 19ns Switching Speed
- GaAs pHEMT Technology

## **BARE DIE**

2.11 mm x 1.91 mm x 0.10 mm

100% RoHS Compliant

# **APPLICATIONS**

- Broadband Communications
- Test Instrumentation
- Fibre Optics
- Military
- Aerospace



## **Typical Performance**

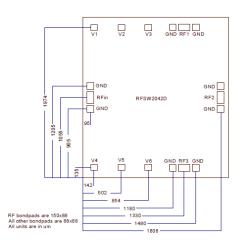
Parameter	Min	TYP	Max	Unit	Conditions
Operating Frequency			20	GHz	
Insertion Loss (1GHz to 5GHz)		1.4	2	dB	ON State
Insertion Loss (>5GHz to 10GHz)		1.3	2.2	dB	ON State
Insertion Loss (>10GHz to 15GHz)		1.5	2.25	dB	ON State
Insertion Loss (>15GHz to 20GHz)		1.6	2.5	dB	ON State
Isolation (1GHz to 20GHz)	37.5	42		dB	ON State (measured at inactive port)
Input Return Loss (1GHz to 20GHz)	12	14		dB	ON State
Output Return Loss (1GHz to 20GHz)	11	12		dB	ON State
OIP2		57		dBm	100MHz spacing
OIP3	28	32		dBm	100MHz spacing
Switching Speed		19		ns	50% Control to 90% RF
Control Current		30	50	μΑ	Sum of all control lines
Control Voltage	-3	-5	-8	VDC	
Switching Speed		19		ns	50% control to 90% RF
Control Current		34	60	μΑ	Sum of all control lines
Control Voltage	-3	-5	-8	VDC	
Control Voltage	-3	-5	-8	V <sub>DC</sub>	

Electrical Specifications,  $T_A$ =+25 °C,  $V_{CTRL}$ =-5  $V_{DC}$ 

## Absolute Maximum Ratings<sup>1</sup>

Parameter	Rating	Unit
Drain Bias Voltage (V <sub>CTRL</sub> )	-10	VDC
RF Input Port Power	+30	dBm
Storage Temperature	-40 to +150	°C
Operating Temperature	-40 to +85	°C

## **Die Layout**



Die Size	Die Thickness
(μm)	(μm)
1910 x 2110	100

Min. Bond Pad Pitch (μm)	Min. Bond Pad Opening (μm x μm)		
150	88x88		



#### **Pad Names and Description**

Name	Description	Interface Schematic
RFIN	RF input. This pad is DC coupled and matched to $50\Omega from  DC$ to $20 GHz$ .	RFIN O———
RF1, RF2, RF3	RF output. This pad is DC coupled and matched to $50\Omega$ from DC to $20\text{GHz}$ .	S RFout
V1, V2, V3, V4, V5, V6	DC control pad for switch operation. Nominal operating voltage is -5V.	\$\frac{1}{2}\text{kohm}\$ \$5pF
GND	Provides ground path for probe measurements.	

#### **Truth Table**

Control Line			RF Path			
V1	V2	V3	V4	V5	V6	
0	-5	-5	-5	0	0	RFIN – RF1
-5	0	0	-5	-5	0	RFIN – RF2
-5	-5	0	0	0	-5	RFIN – RF3
-5	-5	0	-5	0	0	RFOFF (high isolation)



Caution! ESD sensitive device

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied. RoHS status based on EUDirective2002/95/EC (at time of this document revision).

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#### **Preferred Assembly Instructions**

GaAs devices are fragile and should be handled with great care. Specially designed collets should be used where possible.

The back of the die is metallized and the recommended mounting method is by the use of conductive epoxy. Epoxy should be applied to the attachment surface uniformly and sparingly to avoid encroachment of epoxy on to the top face of the die and ideally should not exceed half the chip height. For automated dispense Ablestick LMISR4 is recommended. For manual dispense Ablestick 84-1 LMI or 84-1 LMIT are recommended. These should be cured at a temperature of 150°C for one hour in an oven especially set aside for epoxy curing only. If possible, the curing oven should be flushed with dry nitrogen. The gold-tin (80% Au 20% Sn) eutectic die attach has a melting point of approximately 280°C but the absolute temperature being used depends on the leadframe material used and the particular application. The time at maximum temperature should be kept to a minimum.

This part has gold (Au) bond pads requiring the use of gold (99.99% pure) bondwire. It is recommended that 25µm diameter gold wire be used. Recommended lead bond technique is thermocompression wedge bonding with 0.001" (25µm) diameter wire. Bond force, time, stage temperature, and ultrasonics are all critical parameters and the settings are dependent on the setup and application being used. Ultrasonic or thermosonic bonding is not recommended.

Bonds should be made from the die first and then to the mounting substrate or package. The physical length of the bondwires should be minimized especially when making RF or ground connections.

#### **Handling Precautions**

To avoid damage to the devices, care should be exercised during handling. Proper Electrostatic Discharge (ESD) precautions should be observed at all stages of storage, handling, assembly, and testing.



#### **ESD/MSL Rating**

These devices should be treated as Class 0B (125V to <250V) using the human body model as defined in JEDEC Standard No. JS-001 and subsequent revisions of this standard.

Further information on ESD control measures can be found in MIL-STD-1686 and MIL-HDBK-263. This is an unpackaged part and therefore no MSL rating applies.

#### Reliability

An MTTF in excess of 4 million hours at a channel temperature of 150°C is achieved for the process used to manufacture this device.

#### **Disclaimers**

This product is not designed for use in any space based or life sustaining/supporting equipment.

#### **Ordering Information**

DELIVERY QUANTITY	DELIVERY QUANTITY
Full Pack (100)	SR1320AD - 100
Small Quantity (25)	SR1320AD - 025
Sample Quantity (3)	SR1320AD - 003

